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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details


Product Status	Obsolete
Core Processor	S08
Core Size	8-Bit
Speed	20MHz
Connectivity	I ² C, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	4
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	8-SOIC (0.154", 3.90mm Width)
Supplier Device Package	8-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s08qg84cdner



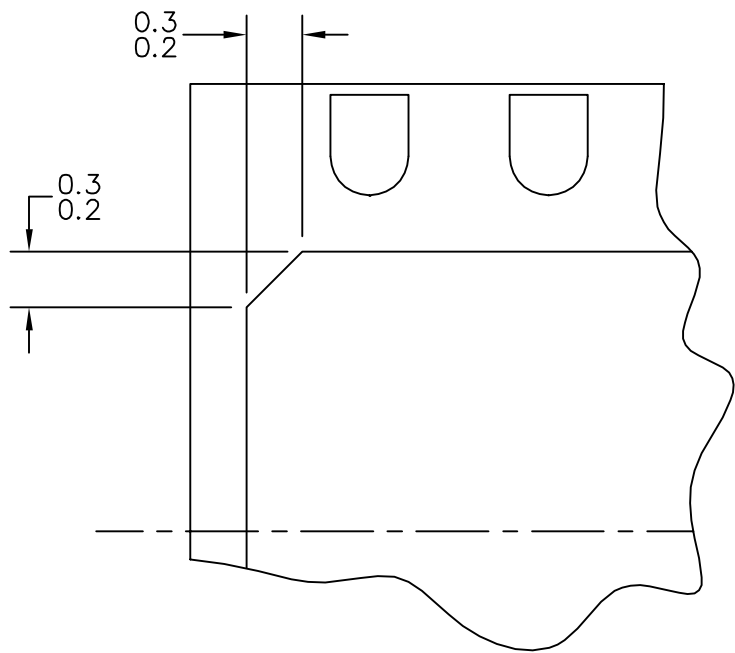
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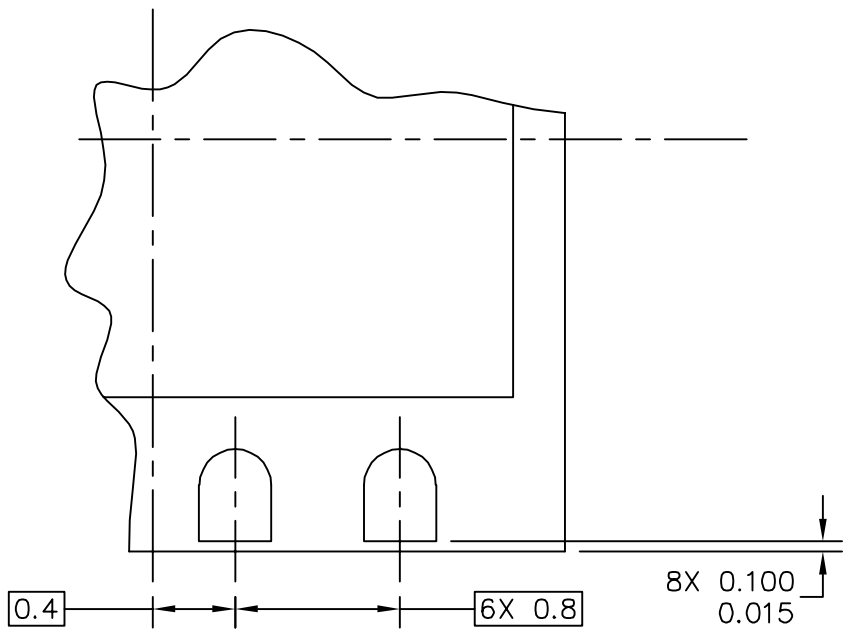
NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
- 3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF–PQFN.
- 4.  COPLANARITY APPLIES TO LEADS, CORNER LEADS, AND DIE ATTACH PAD.
- 5. MIN METAL GAP SHOULD BE 0.2MM.

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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 16 TERMINAL, 0.8 PITCH (5 X 5 X 1) CASE OUTLINE			DOCUMENT NO: 98ARE10614D		REV: 0
			CASE NUMBER: 1679-01		23 MAR 2005
			STANDARD: FREESCALE		



DETAIL M
BACKSIDE PIN 1 INDEX



DETAIL N

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TITLE: THERMALLY ENHANCED DUAL FLAT NO LEAD PACKAGE (DFN) 8 TERMINAL, 0.8 PITCH (4 X 4 X 1)	DOCUMENT NO: 98ARL10557D		REV: B	
	CASE NUMBER: 1452-02		28 DEC 2005	
	STANDARD: NON-JEDEC			